



## Material Content Data Sheet



Sales Product Name	TLE4254EJ A			Issued		16. January 2020		
MA#	MA001675670							
Package	PG-DSO-8-27			Weight*		84.18 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.779	2.11	2.11	21130	21130
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.728	0.86		8645	
	non noble metal	copper	7440-50-8	29.548	35.10	36.01	351025	360210
wire	noble metal	gold	7440-57-5	0.110	0.13	0.13	1310	1310
encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1173	
	plastics	epoxy resin	-	4.543	5.40		53973	
	inorganic material	silicondioxide	60676-86-0	44.740	53.15	58.67	531512	586658
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8258	8258
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8607	8607
glue	plastics	epoxy resin	-	0.291	0.35		3457	
	noble metal	silver	7440-22-4	0.873	1.04	1.39	10370	13827
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com